



Standard Practice for Ensuring Test Consistency in Neutron-Induced Displacement Damage of Electronic Parts¹

This standard is issued under the fixed designation E1854; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This practice sets forth requirements to ensure consistency in neutron-induced displacement damage testing of silicon and gallium arsenide electronic piece parts. This requires controls on facility, dosimetry, tester, and communications processes that affect the accuracy and reproducibility of these tests. It provides background information on the technical basis for the requirements and additional recommendations on neutron testing.

1.2 Methods are presented for ensuring and validating consistency in neutron displacement damage testing of electronic parts such as integrated circuits, transistors, and diodes. The issues identified and the controls set forth in this practice address the characterization and suitability of the radiation environments. They generally apply to reactor sources, accelerator-based neutron sources, such as 14-MeV DT sources, and ²⁵²Cf sources. Facility and environment characteristics that introduce complications or problems are identified, and recommendations are offered to recognize, minimize or eliminate these problems. This practice may be used by facility users, test personnel, facility operators, and independent process validators to determine the suitability of a specific environment within a facility and of the testing process as a whole. Electrical measurements are addressed in other standards, such as Guide F980. Additional information on conducting irradiations can be found in Practices E798 and F1190. This practice also may be of use to test sponsors (organizations that establish test specifications or otherwise have a vested interest in the performance of electronics in neutron environments).

1.3 Methods for the evaluation and control of undesired contributions to damage are discussed in this practice. References to relevant ASTM standards and technical reports are provided. Processes and methods used to arrive at the appropriate test environments and specification levels for electronics

systems are beyond the scope of this practice; however, the process for determining the 1-MeV equivalent displacement specifications from operational environment neutron spectra should employ the methods and parameters described herein. Some important considerations and recommendations are addressed in [Appendix X1](#) (Nonmandatory information).

1.4 The values stated in SI units are to be regarded as standard. No other units of measurement are included in this standard.

1.5 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 The ASTM standards listed below present methods for ensuring proper determination of neutron spectra and fluences, gamma-ray doses, and damage in silicon and gallium arsenide devices. The proper use of these standards is the responsibility of the radiation metrology or dosimetry organization affiliated with facility operations. The references listed in each standard are also relevant to all participants as background material for testing consistency.

2.2 ASTM Standards:²

- E170 Terminology Relating to Radiation Measurements and Dosimetry
- E181 Test Methods for Detector Calibration and Analysis of Radionuclides
- E261 Practice for Determining Neutron Fluence, Fluence Rate, and Spectra by Radioactivation Techniques
- E262 Test Method for Determining Thermal Neutron Reaction Rates and Thermal Neutron Fluence Rates by Radioactivation Techniques
- E263 Test Method for Measuring Fast-Neutron Reaction Rates by Radioactivation of Iron

¹ This practice is under the jurisdiction of ASTM Committee E10 on Nuclear Technology and Applications and is the direct responsibility of Subcommittee E10.07 on Radiation Dosimetry for Radiation Effects on Materials and Devices.

Current edition approved June 1, 2013. Published July 2013. Originally approved in 1996. Last previous edition approved in 2007 as E1854 - 07. DOI: 10.1520/E1854-13.

² For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

E264 Test Method for Measuring Fast-Neutron Reaction Rates by Radioactivation of Nickel

E265 Test Method for Measuring Reaction Rates and Fast-Neutron Fluences by Radioactivation of Sulfur-32

E393 Test Method for Measuring Reaction Rates by Analysis of Barium-140 From Fission Dosimeters

E481 Test Method for Measuring Neutron Fluence Rates by Radioactivation of Cobalt and Silver

E482 Guide for Application of Neutron Transport Methods for Reactor Vessel Surveillance, E706 (IID)

E496 Test Method for Measuring Neutron Fluence and Average Energy from $^3\text{H}(d,n)^4\text{He}$ Neutron Generators by Radioactivation Techniques

E523 Test Method for Measuring Fast-Neutron Reaction Rates by Radioactivation of Copper

E526 Test Method for Measuring Fast-Neutron Reaction Rates by Radioactivation of Titanium

E666 Practice for Calculating Absorbed Dose From Gamma or X Radiation

E668 Practice for Application of Thermoluminescence-Dosimetry (TLD) Systems for Determining Absorbed Dose in Radiation-Hardness Testing of Electronic Devices

E704 Test Method for Measuring Reaction Rates by Radioactivation of Uranium-238

E705 Test Method for Measuring Reaction Rates by Radioactivation of Neptunium-237

E720 Guide for Selection and Use of Neutron Sensors for Determining Neutron Spectra Employed in Radiation-Hardness Testing of Electronics

E721 Guide for Determining Neutron Energy Spectra from Neutron Sensors for Radiation-Hardness Testing of Electronics

E722 Practice for Characterizing Neutron Fluence Spectra in Terms of an Equivalent Monoenergetic Neutron Fluence for Radiation-Hardness Testing of Electronics

E798 Practice for Conducting Irradiations at Accelerator-Based Neutron Sources

E844 Guide for Sensor Set Design and Irradiation for Reactor Surveillance, E 706 (IIC)

E944 Guide for Application of Neutron Spectrum Adjustment Methods in Reactor Surveillance, E 706 (IIA)

E1018 Guide for Application of ASTM Evaluated Cross Section Data File, Matrix E706 (IIB)

E1249 Practice for Minimizing Dosimetry Errors in Radiation Hardness Testing of Silicon Electronic Devices Using Co-60 Sources

E1250 Test Method for Application of Ionization Chambers to Assess the Low Energy Gamma Component of Cobalt-60 Irradiators Used in Radiation-Hardness Testing of Silicon Electronic Devices

E1297 Test Method for Measuring Fast-Neutron Reaction Rates by Radioactivation of Niobium

E1855 Test Method for Use of 2N2222A Silicon Bipolar Transistors as Neutron Spectrum Sensors and Displacement Damage Monitors

E2005 Guide for Benchmark Testing of Reactor Dosimetry in Standard and Reference Neutron Fields

E2450 Practice for Application of $\text{CaF}_2(\text{Mn})$ Thermoluminescence Dosimeters in Mixed Neutron-Photon Environments

F980 Guide for Measurement of Rapid Annealing of Neutron-Induced Displacement Damage in Silicon Semiconductor Devices

F1190 Guide for Neutron Irradiation of Unbiased Electronic Components

3. Functional Responsibilities

3.1 The following terms are used to identify key roles and responsibilities in the process of reactor testing of electronics. Some participants may perform more than one role, and the relationship among the participants may differ from test program to test program and from facility to facility.

3.2 *Sponsor*—Individual or organization requiring the test results and ultimately responsible for the test specifications and use of the results (for example, a system developer or procuring activity). Test sponsors should consider the objectives of the test and the issues raised in this practice. They shall clearly communicate to the user the test requirements, including specific test methods.

3.3 *User*—Generally, the individual or team who contracts for the use of the facility, specifies the characteristics needed to accomplish the test objectives, and makes sure that the documentation of the test parameters is complete. If the test sponsor does not communicate clear requirements and sufficient information to fully interpret them, the user shall communicate to the sponsor, prior to the test, the assumptions made and any limitations of applicability of test data because of these assumptions. This may require consultation with a test specialist, who may be internal or external to the user organization. Facility users also should consider the objectives of their tests and the issues raised in this practice. The user may also conduct the tests. The user shall communicate the environmental, procedural (including specific test methods, if any) and reporting requirements to the other participants including the tester, the facility operators, and the test specialist.

3.4 *Facility Organization*—The group responsible for providing the radiation environment. The facility organization shall provide pre-test communication to the user on facility capabilities, cautions, and limitations, as well as dosimetry capabilities, characteristics of the test environment, and test consistency issues unique to the facility and/or test station within the facility. If there is no independent validator, the facility shall also be required to provide the user with documentation on the controls, calibrations, and validation tests, which verify its suitability for the proposed tests. Post-test, the facility shall report dosimetry results, relevant operational parameters, and any occurrences that might affect the test results. The radiation facility and test station used in the test shall meet the criteria specified in Section 5.

3.5 *Dosimetry Group*—Individual or team providing data of record on dose, dose rate, neutron fluence, and spectra.

3.6 *Test Specialist*—Individual providing radiation test expertise. This individual may identify the appropriate damage

function(s) and may fold them with neutron spectra to determine/predict damage and damage ratios. This individual may also provide information on experiment limitations, custom configurations that are advantageous, and interpretation of dosimetry results.

3.7 Validator—Independent person who may be responsible for verifying either the suitability of the radiation environment, the quality of the radiation test including the electrical measurements, or the radiation hardness of the electronic part production line.

4. Significance and Use

4.1 This practice was written primarily to guide test participants in establishing, identifying, maintaining, and using suitable environments for conducting high quality neutron tests. Its development was motivated, in large measure, because inadequate controls in the neutron-effects-test process have in some past instances resulted in exposures that have differed by factors of three or more from irradiation specifications. A radiation test environment generally differs from the environment in which the electronics must operate (the operational environment); therefore, a high quality test requires not only the use of a suitable radiation environment, but also control and compensation for contributions to damage that differ from those in the operational environment. In general, the responsibility for identifying suitable test environments to accomplish test objectives lies with the sponsor/user/tester and test specialist part of the team, with the assistance of an independent validator, if available. The responsibility for the establishment and maintenance of suitable environments lies with the facility operator/dosimetrist and test specialist, again with the possible assistance of an independent validator. Additional guidance on the selection of an irradiation facility is provided in Practice F1190.

4.2 This practice identifies the tasks that must be accomplished to ensure a successful high quality test. It is the overall responsibility of the sponsor or user to ensure that all of the required tasks are complete and conditions are met. Other participants provide appropriate documentation to enable the sponsor or user to make that determination.

4.3 The principal determinants of a properly conducted test are: (1) the radiation test environment shall be well characterized, controlled, and correlated with the specified irradiation levels; (2) damage produced in the electronic materials and devices is caused by the desired, specified component of the environment and can be reproduced at any other suitable facility; and (3) the damage corresponding to the specification level derived from radiation environments in which the electronics must operate can be predicted from the damage produced by the test environment. In order to ensure that these requirements are met, system developers, procurers, users, facility operators, and test personnel must collectively meet all of the essential requirements and effectively communicate to each other the tasks that must be accomplished and the conditions that must be met. Criteria for determining and maintaining the suitability of neutron radiation environments for 1-MeV equivalent displacement damage testing of electron-

ics parts are presented in Section 5. Mandatory requirements for test consistency in neutron displacement damage testing of electronic parts are presented in Section 5. Additional background material on neutron testing and important considerations for gamma dose and dose rate effects are presented in (non-mandatory) Appendix X1 and Appendix X2, but compliance is not required.

4.4 Some neutron tests are performed with a specific end application for the electronics in mind. Others are performed merely to ensure that a 1-MeV-equivalent-displacement-damage-specification level is met. The issues and controls presented in this practice are necessary and sufficient to ensure consistency in the latter case. They are necessary but may not be sufficient when the objective is to determine device performance in an operational environment. In either case, a corollary consistency requirement is that test results obtained at a suitable facility can be replicated within suitable precision at any other suitable facility.

4.4.1 An objective of radiation effects testing of electronic devices is often to predict device performance in operational environments from the data that is obtained in the test environments. If the operational and test environments differ materially from each other, then damage equivalence methodologies are required in order to make the required correspondences. This process is shown schematically in Fig. 1. The part of the process (A, in Fig. 1) that establishes the operational neutron environments required to select the appropriate 1-MeV-equivalent specification level, or levels, is beyond the scope of this practice. However, if a neutron spectrum is used to set a 1 MeV equivalent fluence specification level, it is important that the process (B, in Fig. 1) be consistent with this practice. Damage equivalence methodologies must address all of the important contributors to damage in the operational and test environments or the objectives of the test may not be met. In the mixed neutron-gamma radiation fields produced by nuclear reactors, most of the permanent damage in solid-state semiconductor devices results from displacement damage produced by fast neutrons through primary knock-on atoms and their associated damage cascades. The same damage functions must be used by all test participants to ensure damage equivalence. Damage functions for silicon and gallium arsenide are provided in the current edition of Practice E722 (see Note 1). At present, no damage equivalence methodologies for

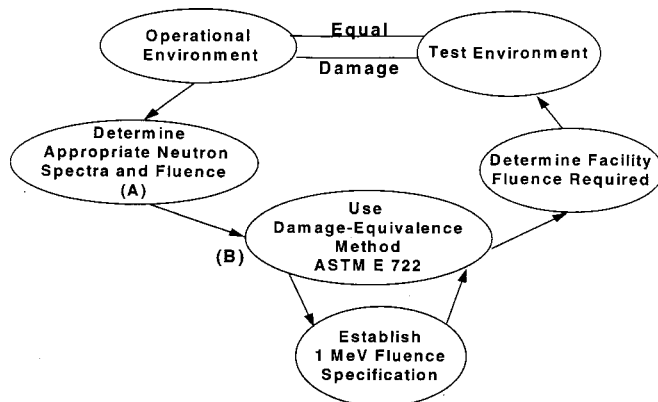


FIG. 1 Process for Damage Equivalence

neutron displacement damage have been developed and validated for semiconductors other than silicon and gallium arsenide.

NOTE 1—Pre-1993 editions of Practice E722 reference outdated versions of the silicon damage function and do not include GaAs damage functions. However, when comparing test specifications and test results from data obtained in historical tests, it may be necessary to adjust specifications and test data to account for changes in damage functions which have evolved through the years as more accurate and reliable damage functions have become available.

4.4.2 If a 1-MeV equivalent neutron fluence specification, or a neutron spectrum, is provided, the damage equivalence methodology, shown schematically in Fig. 1, is used to ensure that the correct neutron fluence is provided and that the damage in devices placed in the exposure position correlates with the displacement energy from the neutrons at that location.

5. Requirements for Neutron Displacement Damage Testing

5.1 This section identifies the requirements that must be met to ensure consistency in neutron displacement damage testing of electronics.

5.2 *Test Specification*—The sponsor or procuring group specifies the radiation test levels. Frequently, 1-MeV equivalent (Si) fluence levels are specified. The damage equivalence methodology and parameters used to determine the 1-MeV fluence shall be in accordance with Practice E722.

5.2.1 (Optional) If desired by the sponsor/user/tester, together they determine if the test specifications are adequate to obtain the sponsor's test objectives. The first steps are to examine the characteristics of the operational environment where the devices are to perform, to choose the devices to be tested, and to determine the important damage parameters to be evaluated. Next, a radiation environment must be chosen that can meet the sponsor's test objectives and be effectively used to evaluate the responses of the required device parameters to the radiation environment. This step may require the support of a test specialist and the facility operators.

5.3 *Sources*—The test station may be in or near a fast-burst reactor or a pool-type reactor (such as a TRIGA). A 14-MeV or ^{252}Cf neutron source also may be used. Operation may be in either pulse or steady state mode, as appropriate. The source shall be one that is acceptable to the sponsor. Preferred sources and test locations are those in which device damage contributions from anything other than fast neutrons are negligible (see Appendix X1).

5.4 *Environment Characterization*—It is assumed throughout the standard that the primary damage mechanism being investigated is the neutron displacement damage. If secondary effects (such as those caused by ionizing radiation) contribute to the response of the device, these processes must be taken into account in interpreting the test results. These issues are discussed in 5.12.1 and 5.12.2. The neutron environment is characterized by a neutron spectrum measurement.

5.4.1 At a minimum, the facility shall provide the experimenter with a neutron spectrum representing the free-field environment at the "Device Under Test" (DUT) location. This spectrum determination shall be derived with a methodology

that gives appropriate weight to experimental measurements. These methodologies may include use of activation sensors within an iterative or least-squares spectrum adjustment code. (See Guides E720 and E721.) A free-field spectrum based solely upon neutron transport calculations for a reactor irradiation is not acceptable. Physics constraints associated with some accelerator-based neutron sources may be sufficient for spectrum characterization when used in conjunction with normalization measurements such as are described in Test Method E496 for 14-MeV DT sources. Neutron spectra from isotopic sources, such as ^{252}Cf , may be used to leverage spectrum determinations performed at other facilities as long as the irradiation source and geometry are sufficiently similar. It is acceptable that the experimental measurements supporting the spectrum characterization be performed at a different, but near-by, location rather than the characterized position, as long as one can use calculations to relate the sensor response between the characterized position and the location where the sensors are fielded and if the analysis is accompanied by a high fidelity assessment of the calculated ratio of the sensor response in the two positions.

5.4.1.1 If the fixtures used by the experimenter significantly perturb the free-field environment that was characterized by the facility, then the experimenter shall be responsible for properly relating the irradiation environment impacting the device-under-test to the freefield radiation environment characterization that is provided by the facility.

NOTE 2—The determination of the spectrum at a location within or near an experimental fixture that perturbs the free-field spectrum is often best accomplished by calculations. Calculations alone may be sufficient in these cases as long as the calculational methodology and modeling have been validated by comparison with measurements for the free-field (unperturbed) case. Experimental validation of any calculations is always desirable, but is not always practical. The use of dosimetry sensors is discussed in Test Methods E181, E262, E393, E481, E523, E526, E704, E705, and E1297, Practice E261, and Guide E844.

5.4.2 For the determination of the spectrum, the sensor set must be sensitive over the energy range within which the device under test is sensitive. In particular, the sensor set shall include a sensor with significant response in the 10-keV to 1-MeV energy region. Sensors with energy responses in this region include the boron-covered fission foils, ^{235}U and ^{239}Pu , as well as the ^{237}Np fission foil. In addition, niobium through the reaction $^{93}\text{Nb}(n,n')^{93m}\text{Nb}$ can be useful, although its very long half-life of about 16 years usually results in a very low activity. In the absence of fission foils, silicon devices can be used effectively as spectrum sensors responsive within this energy range. It is suggested that both fission foils and silicon devices be used for mutual confirmation (1,2).³

5.4.3 To provide information needed to account for possible gamma-ray effects on the DUT, the facility shall provide a measure of the gamma-ray dose to the silicon or gallium arsenide device. The selected gamma-ray sensor shall have been demonstrated to have a low neutron sensitivity. The gamma-ray detector response shall be traceable to NIST standards. One common gamma dose sensor with low neutron

³ The boldface numbers in parentheses refer to a list of references at the end of this practice.

sensitivity is a $\text{CaF}_2\text{:Mn}$ thermoluminescent detector (TLD). LiF TLDs (even LiF TLDs with an enriched ^7Li component) are more sensitive to thermal neutrons than CaF_2 and should only be used with care in fast burst reactors and should be avoided in reactors with a significant thermal neutron fluence rate. Both radiochromic films and alanine show a high neutron sensitivity due to proton recoil in the homogeneous dosimeter material, and are thus not recommended as gamma sensors for mixed neutron/gamma reactor environments.

5.5 Damage Equivalence—The facility shall provide, at 15-month intervals or less, experimental confirmation that the equivalent fluence is consistent with that predicted by the facility-provided spectrum. The emphasis here is on the stability and consistency of the neutron field since the time of the complete spectrum characterization. One way that this may be done is by demonstrating that the displacement damage, as measured with calibrated silicon (or GaAs) device, is equal to that calculated from the spectrum that is attributed to the test environment. The device calibration could be an irradiation in a reference neutron environment, see 5.6, or a reference calibration can be obtained by irradiating the device within the same time period (not necessarily in the same irradiation) as when the baseline experimentally supported spectrum characterization referenced in 5.4 was performed. Two devices appropriate to this application, because of extensive investigations of their responses, are 2N2222A transistors (see Test Method E1855) and DN-156 diodes (3). The neutron-induced displacement damage changes the gain of the transistors in amounts inversely proportional to the 1-MeV equivalent fluence, Φ_1 . In the diodes, the forward voltage increases with fluence in a reproducible, but nonlinear, way (The shape of the calibration curve is the same for all of the diodes.) The environment is considered to be satisfactorily characterized for electronic parts testing if the ratio of the Φ_1 damage value to a reference monitor, such as the $^{58}\text{Ni}(n,p)^{58}\text{Co}$ activity obtained from the simultaneous irradiation of a nickel foil is within 10 % of that predicted using the spectrum and fluence reported by the test facility for that location (see Note 3). Another acceptable way to demonstrate this stability and consistency of the neutron field is to irradiate a subset of sensors that were used in the baseline experimentally supported spectrum characterization (see 5.4) and demonstrate the consistency in the ratio of the sensor response values to a reference/monitor reaction, such as $^{58}\text{Ni}(n,p)^{58}\text{Co}$, with the values obtained during the baseline spectrum characterization. The subset of sensors used must be one that includes sensors with good energy coverage over the range of neutron energies that are important to the displacement damage metric of interest, typically between 10 keV and 5 MeV.

NOTE 3—The damage measurements discussed here are all ratio measurements in reference and test environments taken with the same PH11 monitor. Therefore the damage constant that relates the change in reciprocal gain for 2N2222 transistors (or forward voltage for DN-156 diodes) to displacement damage cancels out.

5.6 Reference Environment—If a reference environment is used for the calibration of the PH11 monitors used in 5.5, this reference neutron field shall be either a standard fast neutron benchmark field (4) or a reference neutron benchmark field (see Guide E2005 and the definitions of “standard neutron

field” and “reference neutron field” in Terminology E170) designated for neutron effects testing in semiconductors. Reference benchmark fields that may be designated for this application are generated by bare fast-fission reactors, either in an in-core cavity or in a nearby leakage environment that is not substantially modified by room-return neutrons. The relevant neutron field parameters must be established by calculation and spectrum measurement in the manner described in Guide E721, and, in addition, must be experimentally verified within an interval no longer than five years and the basis for the experimental verification documented and made available by facility users.

5.7 Delivery of the Characterization Information—The user is responsible for ensuring that he receives the information about the test environment needed to evaluate the response of his DUT. The facility shall be prepared to supply a validated neutron spectrum and associated gamma-ray dose for each test environment. The identification and characterization of secondary effects and conditions that affect the DUT are also necessary. The facility should be prepared to provide uncertainty information about spectrum, fluence, and dose so that the user can evaluate the effect of these uncertainties on the response of the DUT. This information generally reduces to an evaluation of uncertainties in the integral parameters such as Φ_1 , the neutron fluence-to-gamma-ray dose ratio, the fluence greater than 3 MeV, the silicon hardness parameter (defined in Practice E722), the ratio of the fluence greater than 10 keV to the fluence greater than 3 MeV, and the ratio of the total fluence to the fluence greater than 3 MeV.

5.8 Controls and Auditability—The facility (including the reference source FBRs) must provide written assurance that an adequate radiation environment characterization has been performed, that it meets the environment characterization requirements in 5.4 and 5.5, and that the environment has not changed (except for the possible alteration by the test object itself) between the time of the most recent characterization (which was used in the supporting documentation) and the test time. To guard against unaccounted for changes:

5.8.1 The facility shall have adequate in-house procedures for monitoring changes in the reactor configuration between the time at which the experiment takes place and the time the environment characterization took place.

5.8.2 The facility shall confirm in writing that the current environment delivered to the user/tester does not deviate significantly from the environment at which the damage verification and spectral determination were performed.

5.8.3 The facility shall employ a process to inform facility staff responsible for interfacing with users/testers, internal test specialists, and dosimetry specialists of changes that may impact test consistency.

5.8.4 Appropriate neutron and gamma ray monitors shall be included with the DUT on each exposure.

5.9 Dosimetry Equipment—The dosimetry group shall have at a minimum:

5.9.1 Appropriate activation foil counting and gamma dose readout equipment with calibrations traceable to NIST.

5.9.2 Fast neutron threshold activation reactions such as $^{32}\text{S}(n,p)$, $^{54}\text{Fe}(n,p)$, or $^{58}\text{Ni}(n,p)$ shall be used to monitor the

neutron fluence. These reactions are recommended because of their relatively high cross sections and convenient half-lives.

5.9.3 Suitable gamma dose sensors shall be used to monitor the gamma-ray dose discussed in Practice E666. If thermoluminescence dosimeters are selected as the gamma sensor, Practice E668 provides useful information on the calibration and use of TLDs in gamma environments. Practice E2450 provides useful information on the use of TLDs in mixed neutron and gamma ray fields. The sensor selected to monitor the gamma environment should have a demonstrated low neutron sensitivity. $\text{CaF}_2\text{:Mn}$ TLDs are an appropriate sensor for application in most mixed neutron/gamma ray fields.

5.9.4 Calibrated silicon devices may be used as spectrum sensors and 1-MeV equivalent fluence monitors. If silicon devices are used as monitors, then an appropriate device parameter reader must be available along with an oven for annealing treatments.

NOTE 4—Although the dosimetry group is usually associated with the facility in order to ensure continuity of environment characterization, it is often advantageous for the user to add his own dosimetry so that he can more readily monitor consistency with the local dosimetry and the results obtained at other test facilities.

5.10 *Damage Correlations*—For neutron displacement damage equivalence, either the 1-MeV(Si) equivalent fluence or the 1-MeV(GaAs) equivalent fluence must be provided. Alternatively, a neutron spectrum may be provided and the corresponding 1-MeV equivalent fluence specification can be determined using Practice E722. The damage equivalence methodology in this practice has been validated for both silicon and gallium arsenide by demonstrating that equal damage is achieved for the same 1-MeV equivalent fluence even in neutron environments having very different energy distributions (5,6). The spectrum at the test facility exposure location must also be parameterized into a 1-MeV equivalent fluence, Φ_1 , using the same practice. By providing the specified Φ_1 in the test environment, the desired damage is produced and test consistency is achieved if all other contributions to the damage are accounted for or are negligible. The damage equivalence methodology is fully described in Practice E722. It is essential that the proper damage function for the device be used, and accurate spectra for the environments be determined.

5.11 *Test Device Response Function*—Decisions must be made to determine the appropriate response mechanisms in the DUT. After the damage mechanisms have been determined, the correct response functions can be used to calculate the delivered damage level. The latest functions from Practice E722 shall be used for neutron displacement damage functions. Validated damage functions for other semiconductor materials are likely to become available later. If the DUT responds to other components of the environment, these responses must also be characterized for the delivered environment. Secondary effects are discussed in 5.12.1 and 5.12.2.

5.11.1 It is recommended that the tester use a test environment that approximates the operational environment to avoid surprises, especially if a new semiconductor technology is being tested. Alternatively, a free-field or neutron-enhanced fast burst reactor environment may be used to minimize unwanted contributors to damage in a neutron displacement

damage test. A neutron-enhanced environment is produced by shielding the DUT from gamma-rays with a high-Z shield. If environment-modifying materials are used, then separate gamma-ray tests may be called for so that the contributing damage factors can be determined. If gamma filters such as lead or bismuth surround the test object, the neutron spectrum will be modified and must be determined for that configuration.

5.11.2 It is the user/tester's responsibility to make certain that the proper response functions are used for the DUT, but it is the responsibility of the facility or test specialist to make certain that the correct 1-MeV fluence is ascribed to the free-field environment.

5.12 *Device Testing*—This subsection deals primarily with the testing of the DUTs and with the considerations that must be made beyond the basic characterization and maintenance of the test environment.

5.12.1 *Secondary Gamma-Ray Effects*—It is the primary responsibility of the user (with assistance of a test specialist, if desired) to account for the secondary effects that influence device performance. The most important potential contributor to secondary-damage effects is the prompt gamma-ray fluence rate associated with the fission neutron-generation process. The inclusion of gamma sensors in the dosimeter packages allows the potential gamma-ray effects to be evaluated, provided the response of the DUT to gamma rays is determined separately. The response of the DUT to gamma dose shall be determined separately using a pure gamma calibrated source such as ^{60}Co or ^{137}Cs . Frequently encountered gamma-ray effects are discussed further in Appendix X1. The contribution of gamma rays is usually not significant for fast burst reactor tests, unless something that enhances the gamma field is nearby. Guidance for the use of TLDs in gamma fields is found in Practice E668. Practice E2450 describes a procedure for measuring gamma-ray absorbed dose in $\text{CaF}_2\text{(Mn)}$ TLDs exposed to mixed neutron-photon environments.

5.12.2 *Other Secondary Effects*—Other potential contributors to measured DUT performance include displacement damage annealing (which can actually aid in device performance recovery), the temperature and device electrical currents at which the device performance is tested, and displacements caused by thermal neutron capture in trace contaminants and dopants in the electronic parts. For example, boron is frequently used as a dopant in silicon parts and high energy recoil alpha particles can result from these thermal neutron interactions. Gamma dose enhancement effects can be induced in devices at interfaces between materials with dissimilar atomic number. Dose enhancement effects are discussed in Practice E1249 and Test Method E1250.

5.12.3 *Measurements for the DUT Environment*—The neutron fluence used for device irradiation shall be obtained by measuring the amount of radioactivity induced by a fast-neutron threshold activation reaction such as $^{32}\text{S}(n,p)$, $^{54}\text{Fe}(n,p)$, or $^{58}\text{Ni}(n,p)$ in a monitor foil which is irradiated at the same time and co-located with the device. A standard method for converting the measured radioactivity to fluence in the specific monitor foil employed in a neutron environment is given in Test Methods E263, E264, and E265. As discussed in 5.4, the conversion of the foil radioactivity into a neutron fluence

requires a knowledge of the neutron spectrum incident on the foil. If the spectrum is not known, it shall be determined by use of Guide [E720](#) or [E721](#) or Practice [E722](#) or their equivalent.

5.12.4 The determination of (1) the spectrum shape from the environment characterization, and (2) the magnitude of the 1-MeV fluence (derived from the spectrum) with the fluence monitor, completes the characterization of the neutron environment for the test. The user is cautioned that if the neutron spectrum is perturbed, the fluence monitor may no longer provide an accurate measure of the 1-MeV fluence. Additional guidance on the determination of a neutron spectrum by the foil activation method can be found in Guides [E482](#) and [E1018](#), and Practice [E944](#).

5.13 *Test Documentation*—The user, with the assistance of the other participants, is responsible for making certain that all the tasks listed above (in [5.1-5.12](#)) are accomplished and documented. The additional user tasks that must be carried out and documented are DUT performance measurements. If necessary, the sponsor may require the prediction of the device responses in the operational environments based on the test results.

5.13.1 In the usual mode of operation, as discussed in [5.7](#), the facility operator is responsible for providing, characterizing, and reporting on the test environment (the neutron spectrum, fluence, and gamma-ray dose during the test). Such characterizations are to be based on measurements traceable to NIST. The facility operator and test specialist evaluate the test specifications with respect to the capabilities of the facility and provide the documentation on the certified environments that are available to the user. Facility changes possibly affecting the test spectrum that have been made since the last spectrum characterization shall be documented, and the documentation made available to the user. More reliability is achieved if the characterization measurements and the test measurements are both made with the same dosimetry system and procedures, but this is not mandatory.

6. Keywords

6.1 electronics testing; neutron-induced damage; nuclear test reactors; test consistency ; 1 MeV-equivalence

APPENDIXES

(Nonmandatory Information)

X1. RECOMMENDATIONS FOR ENSURING TEST CONSISTENCY

X1.1 This appendix provides additional in-depth discussions and makes recommendations related to the required tasks in Section 5. This expansion of context leads to some repetition in order to preserve continuity. Ideally, all one needs to do is certify that the 1-MeV equivalent fluences in the two environments are the same. The problems in practice are: (1) the neutron environments may not be accurately characterized as to spectral shape or fluence; (2) there may be additional significant contributors to damage; and (3) there may be process faults. This appendix provides recommendations that may be used by test participants to facilitate implementation of the requirements and shed light on the bases for them.

X1.2 It would be very useful for all concerned to have in place a validation process that is independent of both the user and the facility that provides the test environment. It is not practical to make independent validation mandatory. Nevertheless, a spectrum and 1 MeV-equivalent fluence validation methodology has been developed and validated (2) so that determination of suitability of test environments by an independent agency is possible. The process uses a limited set of long half-life foils, silicon transistor monitors, and TLD dosimeters that are exposed in the test environment and read at the validating agency's dosimetry laboratory.

X1.2.1 The user may wish to contract a validator to take on other tasks such as the following: verifying either the suitability of the radiation facility, the quality of the radiation test

including the electrical measurements, or the radiation hardness of the electronic part production line. The responsibility includes confirmation that the requirements of this practice assigned to the facility organization (and external support groups, if used) are met and adequately documented. The documentation may include written procedures for calibration, operation, maintenance, hardware and software configuration control of dosimetry systems, procedures for ensuring the desired environments are obtained, and procedures for tracking parts from door to door within the facility. Upon request, the validator should provide documentation as to the suitability of the test environment(s) to users and to the facility organization.

X1.3 *The Neutron Spectra*

X1.3.1 The spectrum should be determined with an accuracy sufficient to ensure that the derived 1-MeV equivalent fluence is known to $\pm 10\%$ relative to the reference environments discussed in [5.6](#) using the damage function and 1-MeV normalization in Practice [E722](#). The uncertainty in the damage response function itself is not included in this 10 % uncertainty, but it is assumed that all users use the response function listed in Practice [E722](#). Although other means of determining neutron spectra are available, only the multiple-response-function-sensor-method (usually called the foil activation method) is discussed here. Other methods for determining equivalent fluences are mentioned in [X1.6.3](#). Because the method is

discussed thoroughly in Guides E720 and E721, the reader is referred to those standards for the full details.

X1.3.1.1 Use a large number (> 15 if possible) of spectrum sensors, with good spectrum coverage and well-established response functions. Reactions with well established sensitivities have been evaluated for consistency with sets of reactions with overlapping sensitivities. See Guides E720 and E721 for reactions and references to recommended cross sections for use with activation foils. The set of sensors should have sensitivities that cover a neutron energy range that is broader than the energy range to which the DUTs are sensitive. Coverage beyond that range permits interpolation to interior points rather than extrapolation. In the case when a laboratory has no access to fission foils such as ^{235}U and ^{239}Pu , there tends to be a critical gap in sensor set response between 100 keV and 2 MeV. A silicon DUT may have on the order of 70 % of its response in this range in a pool-type reactor environment. In this case, sensitivity in that range can be obtained by using calibrated silicon bipolar transistors (1) or DN-156 diodes (3). Activation foils whose response functions are reaction cross sections are the most commonly used sensors. However, any neutron-sensitive material or device having significant response in the energy and fluence ranges of interest could be qualified as a sensor if its response function is known within reasonable uncertainties. The spectrum adjustment codes can be adapted to use any sensor. The disadvantage of using the PHI1 monitors as spectrum sensors is that then they no longer provide an independent verification of the Φ_1 determined from the spectrum.

X1.3.1.2 The counting laboratory for the activation foils should be able to supply reaction product activities of 20 or more isotopes with a relative accuracy of 5 % or better. The laboratory must maintain calibration procedures that include routine comparisons with primary and secondary NIST-traceable sources.

X1.3.1.3 The sensors should be exposed uniformly in the same configuration as the DUTs. This requires careful attention to a number of factors: (1) Does the material of the experiment alter the spectrum at the DUT? (2) Can the immediate past operating history of the reactor before the test affect the reactor spectrum? In pool-type reactors, for example, the positions of control rods or even power level can affect the spectrum shape. (3) Are the radiation field gradients high enough to necessitate rotating the sensors (in steady state exposures) to ensure that they all see the same field? Large corrections for fluence profiles are seldom satisfactory. (4) If the foils must be stacked, can there be shadowing? (5) Are self-shielding effects possible? Gold foils are particularly vulnerable and should be used in a dilute form (< 0.2 % by weight); otherwise, one must anticipate making corrections for self shielding.

X1.3.1.4 Expertise and experience in using at least one of the currently accepted spectrum adjustment codes such as SAND II, LSL-M2, STAYSL or FERRET are necessary for the proper interpretation of the data. (7-13). The use of SAND II and LSL-M2 is discussed in Guide E721 for application in transient radiation effects on electronics (TREE) tests.

X1.3.2 Testing can be greatly simplified if the neutron spectrum shape in the test environment can be customized so

that it is the same as that in the operational environment. It is always good practice to use a test environment that is as close as possible to the operational environment because the uncertainties introduced in relating them will then be minimized. Fast burst reactors are often the best choice for TREE testing because the spectrum shape approximates that of many specified operational environments. In addition, for free-field exposures the gamma-ray induced permanent damage is usually small compared to that induced by the neutrons. If possible, choose a test environment with a high neutron-to-gamma ratio, Φ_1/γ , so that corrections for gamma-ray effects either are not significant or can be applied easily.

NOTE X1.1—In a reactor environment, if the Φ_1/γ ratio is less than 10^{11} n/cm²/Gy(Si), then the possibility of significant gamma-ray-induced permanent damage in silicon bipolar transistors should be investigated. Some devices such as interdigitated power transistors show significant ionizing dose damage (from gamma rays) even in FBRs.

X1.3.3 Neutron irradiation sources other than FBRs are used for effects testing for a number of reasons. First, the FBR environment may not be available or provide sufficient fluence. Second, for some operational environments, such as endoatmospheric conditions, another environment such as that provided by pool-type reactors may be a better match. These typically provide a spectrum with an enhanced low energy 1/E plus thermal tail, a longer pulse and smaller Φ_1/γ ratio. (The increased risk of gamma-ray contributions to damage is discussed in X1.5.7.) In any case, the spectrum should be determined experimentally for each test environment, or proof obtained that the differences introduced produce insignificant changes in the effects.

X1.3.4 Another complication with pool-type reactors is that the neutron spectrum and, hence, the neutron damage, may be affected by the reactor's operating history, fuel loading, and control rod positions. Verification must be obtained that the conditions were the same during the times of spectrum determination and of the test. Controls should be in place to ensure notification of the dosimetrist or test specialist of reactor changes that might affect the radiation environment at principal test locations. One way to verify that the spectrum has not changed is to compare the various ratios of the activities from the reactions $^{32}\text{S}(n,p)^{32}\text{P}$, $^{56}\text{Fe}(n,p)^{56}\text{Mn}$, $^{55}\text{Mn}(n,\gamma)^{56}\text{Mn}$, and $^{197}\text{Au}(n,\gamma)^{198}\text{Au}$ with those obtained during the spectrum measurement. If significant changes in the ratios are observed (± 5 %), then a new spectrum determination is required. [If the exposures are long compared to the half-lives of the foils suggested above, then the first three might be replaced by $^{54}\text{Fe}(n,p)^{54}\text{Mn}$, $^{48}\text{Ti}(n,p)^{48}\text{Sc}$, and $^{45}\text{Sc}(n,\gamma)^{46}\text{Sc}$]. Calibrated silicon transistors can also be used to help monitor environment changes (1).

X1.3.5 Irradiation by ^{252}Cf may be suitable in instances when the typically low fluence available can be accommodated (such as with very sensitive devices). Although the undegraded spontaneous-fission neutron spectrum shape is well documented, materials around the source can severely modify the radiation field. An evaluation must be made of the need to measure the spectrum as opposed to assuming the source to be adequately characterized by the pure ^{252}Cf spontaneous fission neutron spectrum.

X1.4 Neutron Fluence

X1.4.1 The monitor that is exposed with the DUT should usually be of the same kind as one of the sensors used in the spectrum determination. Its response in the test environment should be compared to the calculated response in the spectrum-measurement exposure to normalize the fluence. This minimizes systematic error. (It is assumed that during the spectrum-measurement process, the difference between the measured and calculated response is small, indicating good agreement between the sensor response and the spectrum characterization.) Sulfur or nickel foils are typical monitor foils because of their favorable sensitivity and half-lives. As with the other sensors, the dosimetry laboratories must maintain a regular calibration schedule with comparison against NIST standards to ensure that shifts have not occurred in the time between the spectrum determination and the DUT tests.

X1.4.2 One advantage of foils as neutron monitors is that they are generally very insensitive to gamma rays. They also exhibit uniformity, known decay, and lack of sensitivity to temperature and humidity. (If very hard gamma rays, $E > \sim 10$ MeV, are present, then γ, p and γ, n photoneutron reactions may contribute to foil activation. Examples are $^{57}\text{Fe}(\gamma, p)$ ^{56}Mn and $^{25}\text{Mg}(\gamma, p)$ ^{24}Na . Both of these initial isotopes are present in the natural materials and will contribute daughter elements that will add activity not related to the reaction of interest for neutron fluence determination. The use of isotopically pure ^{56}Fe and ^{24}Mg foils eliminates this problem.) Also, the possibility of photofission reactions in fission foils must be considered. These considerations are usually not important for fission type or modified fission type spectra with a high neutron-to-gamma $[(n/\text{cm}^2)/\text{Gy}(\text{Si})]$ ratio.

X1.5 Contributors to Damage—The identification of the major contributors to device damage is primarily the responsibility of the device user/tester.

X1.5.1 If the contributors to damage and the associated response functions for the DUT are not well defined, then the test environment should closely match the operational environment. Fortunately, the silicon response functions are well established, and a variety of environments, if properly characterized, can be used successfully for simulation tests.

X1.5.2 When the test and operational neutron spectra differ, the equivalent fluence methodology required in Section 5 should be applied to ensure displacement damage equivalence. This approach has been validated for silicon over a period of many years and in many environments.

X1.5.3 In 1979, Verbinski et al. (14) published the results of a study of the gain changes of bipolar 2N2222A transistors induced by neutrons having a variety of energy spectra. In that work, they provided extensive confirmation of “damage equivalence” for silicon. The damage function used was proportional to the energy available for atomic displacement processes from energetic recoils in bulk silicon. They verified two important concepts. First, the change in the reciprocal of the gain in a bipolar device is proportional to the 1-MeV equivalent fluence, Φ_1 , incident on the device. The proportionality constant is K_{τ} . Second, the relative damage induced in

different neutron environments can be predicted, provided the neutron spectra and the silicon damage function are known. The spectra were measured by the foil activation method. Within their experimental uncertainty, they also verified the silicon damage function calculated by Rogers et al. (15).

X1.5.4 Since that time, modifications of the silicon response function have been made by use of the improved NJOY code (16,17) and improved cross sections. This updated displacement kerma function is listed in Practice E722. Also listed is the damage function for GaAs. It has been demonstrated that the updated silicon cross section (18), differs little from the previous version used in Practice E722 below 7 MeV. The displacement kerma function for GaAs is multiplied by an empirically determined shape factor that depends on the initial energy of the knock-on nucleus. It has been speculated that this is a thermal-spike or damage cluster effect; it is not observed in silicon (19).

X1.5.5 Paragraphs X1.3-X1.5.4 discussed the acquisition of the spectrum and damage function information needed to calculate the neutron displacement damage in bulk silicon (or any other material for which the damage function is known). However, as suggested earlier, this is only part of the parts-testing task. The experimenter must next measure, with sufficient accuracy, the effect of the radiation field on his device (the response) and correlate it quantitatively with the relevant characteristics of the radiation field that affect the damage. Each device is different, so the connection between the effect (for example, change in gain) and the damage must be established by a measurement. In this way, the relationship between the radiation field and the effect is established.

X1.5.6 If the tester can arrange for the test and operational environments to be identical, he knows the device response will be the same barring process faults. At the next level, if he knows that the effect in both environments is a function of the 1-MeV equivalent neutron fluence only, and he can arrange it so that $\Phi_{1t} = \Phi_{1o}$, then consistency also is ensured even if the neutron spectrum shapes differ. This assumes that other phenomena do not contribute significantly to the response, or that the effects have been subtracted out.

X1.5.7 Secondary effects that must be accounted for are the following:

X1.5.7.1 In bipolar transistors, ionization caused both by gamma rays and indirectly by neutrons can lead to charge trapping and interface states that affect the gain. In metal-on-silicon transistors (MOS) and integrated circuits, the effects of interface states and trapped charge produced by both gamma-ray and neutron ionization are highly time-dependent. This leads to a complex device response that is a function of ionizing dose, dose rate, and the time between irradiation and device characterization (20). In addition, because of dose-enhancement effects at interfaces between high and low atomic number materials, the dose to a sensitive region of a device can be significantly different from that measured by standard dosimetry techniques (21). This is especially true in the softer photon spectra present in pool reactors.

X1.5.7.2 High energy gamma-rays can indirectly produce displacements in semiconductor crystals. Therefore, if the

fluence rate of hard gamma-rays is high, the displacement damage from gamma rays can be comparable to that induced by neutrons. (For example, a 10-cm thick cadmium loaded polyethylene filter outside an FBR can reduce the Φ_1/γ ratio by a factor of 20). The gamma-ray-induced damage cannot be directly correlated with the neutron spectrum. If the device is tested in a pure gamma ray field so that a scaled version of its response can be subtracted, it is not certain that this response will be the same as that produced during the neutron test unless the photon spectra are the same. One should, nevertheless, always include thermoluminescent detectors along with the neutron monitors during tests.

X1.5.7.3 Displacement damage in gallium arsenide depends not only on the displacement kerma, but also on the energy of the primary recoil atoms (19). At this time silicon and gallium arsenide are the only semiconductors with validated damage equivalence models.

X1.5.7.4 Thermal neutrons can produce damage through interactions with dopant materials such as boron that are not accounted for in standard damage-equivalence models. There have even been cases in which the natural abundance of fissile materials in the ceramic lids on memory devices is high enough for thermal neutrons to produce fission fragments that damage the devices.

X1.5.8 Semiconductor devices are more complicated than activation foils, and even the measurement of their response has to be carried out with an appreciation for the factors that affect their performance. The electrical characteristics, such as initial gain, and the response to radiation of individual devices may vary by unacceptable amounts, perhaps as high as a factor of two for the same type of device. The radiation sensitivity is reflected directly in K_T . Therefore, to determine a damage constant that is representative of a batch, a large number may have to be exposed (≥ 10), and the standard deviation of the K_T for the calibration batch should be $\sim 5\%$.

X1.5.9 After exposure of bipolar silicon transistors, annealing of defects ($\sim 20\%$ between 0.5 hours and 1 month) lead to a recovery of gain that necessitates annealing corrections, annealing treatments, or long waiting periods before measurements are carried out. Even a measurement on each transistor, at the same time interval after each exposure, must be handled carefully because after the second exposure, there are two populations of displaced atoms annealing at different rates. It has also been observed that the process of measurement (current injection) may alter the DUT performance. Thus, additional measurements may give different results. Furthermore, the response that is measured depends on the temperature of the device during the measurement (1), and above a certain accumulated exposure the reduction of the base transit time makes the damage nonlinear with respect to fluence. Because of these effects and those in X1.5.8 that experimentally impose uncertainties onto the gain measurements, it is important to deliver enough radiation to induce gain changes much larger than the uncertainties. This is because the damage is proportional to the difference in the reciprocal of the gains before (h_{FEO}) and after (h_{FEO}) exposure.

If this difference, $1/h_{\text{FEO}} - 1/h_{\text{FEO}}$, is small, the fractional error in the damage can be magnified by as much as $(h_{\text{FEO}} + h_{\text{FEO}})/(h_{\text{FEO}} - h_{\text{FEO}})$.

NOTE X1.2—In the testing of large systems, the neutron spectrum and neutron-to-gamma ratio may vary within the system. Therefore, either the environment at each location must be characterized or the uncertainties must be expanded.

X1.6 *The Device Transfer Method of Approximating Φ_1* —There are some test conditions for which the device-transfer method for determining the 1-MeV equivalent fluence in the test environment may prove to be the only option available. This method yields the 1-MeV equivalent fluence without the use of a test environment spectrum. It is a better course than using the wrong spectrum, but provides no confirmation that the damage at the test location correlates directly with the neutron environment. Success in its use depends on the proper accounting for all factors that significantly affect the device performance, but any factors that depend on the neutron spectrum cannot be properly treated. It is recommended, in this case, to apply the method only to silicon bipolar devices or diodes in situations in which the gamma-ray response of the monitors is small (because the DUT may differ from the PHI1 monitor) and in environments that can be shown to differ only moderately from the one for which a full spectrum determination has been obtained. Since confirmation of the measured 1-MeV equivalent fluence may be lacking, this method must be considered as a secondary level of characterization. Its use must be negotiated between the user and the facility operator.

X1.6.1 The transfer method with transistors provides an estimate of the 1-MeV equivalent fluence, Φ_1 , that can be used to predict silicon device performance in the operational environment. One would need to calibrate a well characterized transistor, such as a 2N2222A (1), or a Harshaw DN-156 diode (3), in a reference environment (whose spectrum is known) and then expose it in the test environment along with the DUT. The calibration determines the damage constant for the device so measurement of its response in the test environment determines the value of $\Phi_1^* = \Delta(1/h)/K_T$. However, this process is inadequate in that it does not verify that the damage in the test environment correlates with neutron displacement damage because other factors such as gamma ray effects may contribute to the damage.)

X1.6.2 It is necessary to account for all the factors that affect the determination of Φ_1 that have been discussed in X1.5. This involves also the determination of the response for secondary effects for both the sensor and the DUT. A strong justification for the use of a silicon monitor as part of a spectrum sensor set is that its measured Φ_1 can be compared to the calculated fluence derived from about 20 other measurements from other sensors. Some risks and advantages of device-transfer method are listed in Table X1.1.

X1.6.3 Because fast burst reactors operated in a free air environment have already been so well characterized (22-26) and their stability of output can be easily maintained over long periods of time, they are suitable for the application of the device-transfer technique, provided that the test and operational environments do not differ excessively from that “free

TABLE X1.1 Foils Versus Devices for Reactor Environment Characterization

Multiple Sensor	Devices
Redundancy	One to two well characterized devices
Determine spectrum	No spectral knowledge
Source for transport code	No spectral knowledge
Works for all materials	Works for material of device (out)
No temperature problem	Temperature sensitive
Well known fading (decay)	Variable fading—compensated by oven annealing
Little gamma sensitivity	Gamma sensitive—gamma sensitivity of DN-156
	Diodes is negligible for most environments
Expensive equipment	Less expensive
Time consuming (experiment and unfolding)	Simple with defined controls
Non-portable	Portable
Some foils difficult to obtain (for example, Pu)	Commercially available, but n/γ response is variable

air” character. In those cases 2N2222A bipolar transistors (1) and Harshaw DN-156 diodes (3) have been shown to be valid indicators of Φ_1 (silicon). Confirmation with additional measurements can be obtained with proton recoil, ionization chamber, and foil activation measurements along with calculated spectra. In fact, transport calculations offer significant additional information that cannot be obtained as yet from the multiple sensor measurements. Specifically, they can provide gamma-ray spectra and fine structure in the neutron spectra. (For damage in silicon, fine structure in the spectrum usually occurs at energies lower than is relevant to semiconductor damage.)

X1.6.4 The multiple sensor and device transfer methods of determining Φ_1 have contrasting advantages and disadvantages. The comparisons are shown in Table X1.1.

NOTE X1.3—Other information on the neutron irradiation of electronic components is included in Practice F1190.

X2. GAMMA RAY EFFECTS IN TEST ENVIRONMENTS

X2.1 The points discussed in this section are relevant in accounting for the secondary effects caused by gamma-rays when neutron damage is being investigated.

X2.2 When the experimenter is choosing an environment for his irradiations, he needs to compare the neutron fluence to gamma-ray dose ratios available. Presumably, when neutron fluence and spectra are determined, an ionizing dose will be measured simultaneously with a gamma sensor such as a thermoluminescent dosimeter. The gamma sensors should have electron equilibrating covers designed for the radiation environment being characterized. One can then calculate the Φ_1/γ ratio and choose the most suitable environment. To do this, one should evaluate the approximate contribution of the undesirable component of the radiation field to the device response, in order to make corrections.

NOTE X2.1—In most cases the neutron response of CaF_2 TLDs is quite small (typically recording a gamma-equivalent response of 1 to 2 % of the actual neutron-induced ionizing dose in silicon). Fortunately, when neutron damage dominates a test, the TLD dose is only used to make a

X1.6.5 Activation foils can be used to provide a spectrum characterization and apply to damage in any material. Foils are not sensitive to environmental effects. Devices are straightforward to use in measurements, but are subject to additional test complications such as temperature effects, dose enhancement, and degradation. They are suitable for frequent checks and for interfacility comparisons.

X1.6.6 With the use of devices alone, there is no confirmation from other sensors that the Φ_1 has been determined properly. When a full sensor set is used to characterize the test environment, the compatibility among all the sensors, including the silicon, confirms the characterization and the Φ_1 . If only silicon or only ^{235}U or ^{239}Pu are used, the confirmation of the spectrum in the 10 keV to 600 keV is lost.

X1.6.7 It is more difficult to show that secondary effects are not contributing to the test device response. If a silicon monitor confirms the test spectrum, it implies that secondary effects, such as ionization response, are not contributing. Another example of a potential problem is the case where the device under test has gold as part of the package. This material may induce photon dose-enhancement effects or excessive activation. With a neutron spectrum and dose measurements available, one can evaluate these effects more reliably.

X1.6.8 Without a spectrum, the inclusion of the usual fast neutron monitors, such as sulfur foils only, is no longer reliable if the operational and simulation environments differ. It is the spectrum shape that permits a connection to be made between the sulfur activity and the device damage. In principle, a PHI1 monitor could be used in place of a spectrum to determine Φ_1 if it has the same response as the DUT.

X1.6.9 With a known spectrum in hand, one can predict the response of any other object or material for which the response function is known.

small correction to the DUT response, and the error introduced by the TLD neutron response will have a negligible effect.

X2.3 Both ionizing dose and dose rate determine the responses that are important in MOS devices because there are both oxide-trapped charge creation and interface-state generation occurring, and their effects on device performance have different time scales. Although the detailed mechanisms are not fully understood, dose rate dependency has also been observed in bipolar integrated circuits. The dose rate effects may be divided into three regimens.

X2.3.1 *Low Dose Rate*—In thin gate oxides, the oxide trapped charge is annealed during exposure. This causes the device response to be dominated by interface state charge. In thick gate oxides or field oxides, the buildup of oxide charge dominates despite the annealing and the creation of interface states.

X2.3.2 *High Dose Rate*—The prompt damage measured a short time after exposure may be dominated by oxide trapped

charge. This may occur at rates between 10^1 and 10^7 Gy(Si)/s. At longer times after exposure, interface states may again dominate.

X2.3.3 Intermediate Dose Rate—These rates may be produced in ^{60}Co gamma cells and other radioactive isotope environments. Since interface state and oxide trapped charge tend to compensate each other, the observed damage rate may actually be less than in either the high or low generation rate environments. Thus, the measured effects may be poor indicators of what the response will be in the operational environment.

NOTE X2.2—In some cases devices exposed at high dose rates can be annealed to determine their response in low dose-rate environment. However, it may not always be possible to simulate high dose-rate effects with lower dose-rate environments. Therefore, devices must sometimes be tested in the rate environment in which they will be used.

X2.4 In tests that require most of the dose to be delivered during a short pulse, the fraction of dose delivered during the pulse must be ascertained. In pool-type reactors, there may be large contributions from both the tail of the pulse and delayed gamma rays from the fission products in the reactor core. The tail contribution may be reduced by specifying a “short rod holdup” time. Then the package may have to be removed from the core very soon after the pulse to reduce the delayed gamma-ray contribution. This contribution can equal or exceed the gamma dose delivered during the pulse, especially if the reactor has recently been operated in a high energy mode (leaving many gamma-ray-emitting fission products in the vicinity of the test volume). Even the positions of material objects such as control rods can have significant effects on dose rates and gamma-ray spectra.

X2.5 It is important that the dose measured by the dosimeter be the same as was deposited in the sensitive regions of the test devices. Because many of these devices have electrodes and conductors incorporating high-Z materials, such as gold, the

high photoelectric cross section can cause injection of more electrons into the sensitive regions of semiconductors than would be the case if electron equilibrium existed (**27,28**). Thus, if the gamma-ray field contains a significant fraction of soft photons, the dose in the device can be much larger than the dose in the dosimeter. An ionization chamber has been designed (**29**) with gold or aluminum electrodes for measuring the relative contribution of soft photons in a gamma-ray field (see Test Method **E1250**). A high ratio of current in the side with Au electrodes compared to that with Al electrodes, (~ 3), indicates soft components that must be eliminated if the dose measurement is to be meaningful (1.25-MeV average energy photons from ^{60}Co produce a ratio of 1.6). Some typical values for these chamber ratios were 1.8 for the Sandia Pulsed Reactor III (SPR III) at 43 cm leakage position, 1.8 for the SPR III cavity, and 3.2 for the Annular Core Research Reactor (ACRR) bare cavity. In configurations in which gamma-ray down scattering (Compton scattering) can take place without enough attenuation, the soft component can have a significant effect. The recommended procedure (**30**) is to line test boxes with 1.5 mm of lead followed by 1.0 mm of aluminum to reduce the soft component. Tests have shown that this lining procedure is very effective in reducing dose-enhancement effects (**31**) (see Practice **E1249**).

X2.6 It is rare that a measured gamma-ray spectrum is available to those testing parts in a reactor environment. It is usually necessary to assume that the simulation and operational environments have the same spectrum character and that it can be approximated by a fission-gamma shape (**32**). At this time, it is not fruitful to develop an equivalent gamma-ray fluence testing methodology. The only recourse is to design the test environment to mimic the operational environment as closely as possible. That is one reason for using radiation filter systems to minimize the effects of undesirable components in the environment.

REFERENCES

- (1) Kelly, J. G., Griffin, P. J., and Luera, T. F., “Use of Silicon Bipolar Transistors as Sensors for Neutron Spectra Determinations,” *IEEE Transactions on Nuclear Science*, Vol NS-38, No. 6, December 1991.
- (2) Kelly, J. G., Griffin, P. J., Raupach, D. C., Daubenspect, T. H., Bennion, J. S., and Newell, D. L., “Interlaboratory Verification of Neutron Spectra Used for the Testing of Electronic Parts,” *IEEE Transactions on Nuclear Science*, Vol NS-40, No. 6, December 1993.
- (3) Heimbach, C. R., *Methodology Investigation, Final Report of Neutron Device Monitor*, report USACSTA-7005, August 1990.
- (4) Grundl, J. A. and Eisenhauer, C. M., *Compendium of Benchmark Neutron Fields for Reactor Dosimetry*, NBSIR 85-3151, National Bureau of Standards (now National Institute for Standards Technology), Gaithersburg, MD 20899, January 1986.
- (5) Sparks, M. H., Flanders, T. M., Williams, J. W., Kelly, J., Sallee, W. W., Roknizadeh, M., and Meason, J. L., “Energy Dependence of Neutron Damage in Silicon Bipolar Transistors,” *IEEE Transactions on Nuclear Science*, Vol 36, No. 6, December 1989, pp. 1904–1911.
- (6) Kelly, J. G., and Griffin, P. J., “Comparison of Measured NJOY Silicon Displacement Damage Ratios with ASTM-E 722 and NJOY Calculated Damage,” *Seventh ASTM-EURATOM Symposium on Reactor Dosimetry*, Strasbourg, France, August 1990, pp. 711–718.
- (7) Griffin, P. J., Kelly, J. G., and VanDenburg, J. W., User’s Manual for SNL-SAND-II Code, Sandia National Laboratories, Albuquerque, NM, report SAND93-3957, April 1994.
- (8) Berg, J., and McElroy, W. M., *A Computer-Automated Iterative Method for Neutron Flux and Spectra Determination by Foil Activation*, Atomic International, Tech. Rep. No. AFWL-TR-67-41, September 1967.
- (9) Kelly, J. G., “Neutron Spectrum Adjustment with SANDII Using Arbitrary Trial Functions,” *Proceedings of the Sixth ASTM-EURATOM Conference*, Jackson Hole, WY, 1987.
- (10) Kelly, J. G., and Vehar, D. W., *Measurement of Neutron Spectra in*

- Varied Environments by the Foil Activation Method with Arbitrary Trails*, SAND87-1330, Sandia National Laboratories, Albuquerque, NM, December 1987.
- (11) Stallman, F. W., *LSL-M2: A Computer Program for Least-Squares Logarithmic Adjustment of Neutron Spectra*, NUREG/CR-4349, ORNL/TM-9933, Oak Ridge National Laboratory, Oak Ridge, TN, March 1985.
 - (12) Perey, F. G., "Least Squares Dosimetry Unfolding: *The Program STAY'SL*," report ORNL/TM-6062, ENDF-254, Oak Ridge National Laboratory, Oak Ridge, TN, 1977.
 - (13) Schmittroth, F., *FERRET Data Analysis Code*, report HEDL-TME 79-10, Hanford Engineering Development Laboratory, Richland, WA, September 1979.
 - (14) Verbinski, V. V., Cassapakis, C., Pease, R. L., and Scott, H. L., "Transistor Damage Characterization by Neutron Displacement Cross Section in Silicon: Experimental," *Nuclear Science and Engineering*, Vol 70, 1979, p. 66-72.
 - (15) Rogers, V. C., Harris, L. Jr., Steinman, D. K., and Bryan, D. E., "Silicon Ionization and Displacement kerma for Neutrons from Thermal to 20 MeV," *IEEE Transactions on Nuclear Science*, Vol NS-22, 2326 (1975); Erratum Vol NS-23, 875 (1976).
 - (16) MacFarlane, R. E., Muir, D. W., and Boicourt, R. M., *The NJOY Nuclear Data Processing System, Volume 1: User's Manual*, Los Alamos National Laboratory, Los Alamos, NM, report LA-9303-M, ENDF-324, May 1982.
 - (17) Luera, T. F., Kelly, J. G., Stein, H. J., Lazo, M. S., Lee, C. E., and Dawson, L. R., "Neutron Damage Equivalence for Silicon, Silicon Dioxide and Gallium Arsenide," *IEEE Transactions on Nuclear Science*, Vol NS-34, No. 6, December 1987.
 - (18) Griffin, P. J., Kelly, J. G., and Luera, T. F., "Effect of ENDF/B-VI Cross Sections on Neutron Dosimetry," *Seventh ASTM-EURATOM Symposium on Reactor Dosimetry*, Strasbourg, France, August 1990.
 - (19) Griffin, P. J., Lazo, M. S., Luera, T. F., and Kelly, J. G., "Characterization of Neutron Radiation Damage in GaAs," *IEEE Transactions on Nuclear Science*, Vol 36, No. 6, December 1990.
 - (20) Browning, J. S., Freshman, C. L., Connors, M. P., and Finney, G. A., "Total Dose Characterization of a CMOS Technology at High Dose Rates and Temperatures," *IEEE Transactions on Nuclear Science*, Vol 35, No. 6, July 1988.
 - (21) Posey, L. D., Wrobel, T. F., Evans, D. C., Beezhold, W., Kelly, J. G., MacCallum, C. D., Coppage, F. N., Luera, T. F., and Lorence, L. J., "MOS-Transistor Radiation Detectors and X-ray Dose Enhancement Effects," *IEEE Transactions on Nuclear Science*, Vol NS-32, No. 6, December 1985.
 - (22) Kelly, J. G., Griffin, P. J., and Fan, W. C., "Benchmarking the Sandia Pulsed Reactor III Cavity Neutron Spectrum for Electronic Parts Calibration and Testing," *IEEE Transactions on Nuclear Science*, Vol 40, No. 6, December 1993.
 - (23) Kaul, D. C., and Egbert, S. D., *Radiation Fluences at the Army Pulse Radiation Facility (APRF) Fast Reactor*, Science Application International Corporation, SAIC 90/1286, San Diego, CA, July 1990.
 - (24) Ing, H., et al., *To Determine the Neutron Leakage Spectrum from the Critical Facility at Aberdeen Proving Ground, Maryland*, BTI-89/3-30, March 1989.
 - (25) McGarry, E. D., Kazi, A. H., Davis, G. S., and Gillian, D. M., "Absolute Neutron-Flux Measurement at Fast Pulse Reactors with Calibration Against Californium-252," *IEEE Transactions in Nuclear Science*, Vol NS-23, No. 6, December 1976.
 - (26) Flanders, T. M., Sparks, M. H., and Sallee, W. W., "Radiation Environment Produced by the White Sands Missile Range MoLLY-G Reactor," in *Physics, Safety, and Applications of Pulse Reactors*, 13-17 Nov. 1994, Washington, D.C., American Nuclear Society, pp. 137-144.
 - (27) Wall, J. A., and Burke, E. A., "Gamma Dose Distributions at and Near the Interface of Different Materials," *IEEE Transactions on Nuclear Science*, Vol NS-17, No. 6, 1970, p. 305.
 - (28) Dozier, C. M., and Brown, D. B., "The Use of Low Energy X-rays for Device Testing—A Comparison with Co-60 Radiation," *IEEE Transactions on Nuclear Science*, Vol NS-30, No. 6, December 1983, p. 4382.
 - (29) Kerris, K., and Gorbics, S. G., "Experimental Determination of the Low-Energy Spectral Component of Cobalt-60 Sources," *IEEE Transactions on Nuclear Science*, Vol NS-32, No. 6, December 1985.
 - (30) Brown, D. B., and Dozier, C. M., "Reducing Errors in Dosimetry Caused by Low Energy Components of Co-60 and Flash X-ray Sources," *IEEE Transactions on Nuclear Science*, Vol NS-29, No. 6, 1996 (1982).
 - (31) Kelly, J. G., Luera, T. F., Posey, L. D., Vehar, D. W., Brown, D. B., and Dozier, C. M., "Dose Enhancement Effects in MOSFET IC's Exposed in Typical ⁶⁰Co Facilities," *IEEE Transactions on Nuclear Science*, Vol NS-30, No. 6, December 1983.
 - (32) Keepin, G. R., *Physics of Nuclear Kinetics*, Addison-Wesley Publishing Company, Reading, MA, 1965.

ASTM International takes no position respecting the validity of any patent rights asserted in connection with any item mentioned in this standard. Users of this standard are expressly advised that determination of the validity of any such patent rights, and the risk of infringement of such rights, are entirely their own responsibility.

This standard is subject to revision at any time by the responsible technical committee and must be reviewed every five years and if not revised, either reapproved or withdrawn. Your comments are invited either for revision of this standard or for additional standards and should be addressed to ASTM International Headquarters. Your comments will receive careful consideration at a meeting of the responsible technical committee, which you may attend. If you feel that your comments have not received a fair hearing you should make your views known to the ASTM Committee on Standards, at the address shown below.

This standard is copyrighted by ASTM International, 100 Barr Harbor Drive, PO Box C700, West Conshohocken, PA 19428-2959, United States. Individual reprints (single or multiple copies) of this standard may be obtained by contacting ASTM at the above address or at 610-832-9585 (phone), 610-832-9555 (fax), or service@astm.org (e-mail); or through the ASTM website (www.astm.org). Permission rights to photocopy the standard may also be secured from the ASTM website (www.astm.org/COPYRIGHT/).